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Typed or Printed Name of Person Mailing Paper or Fee: Patricia Aguilon

Signature: Pat Ag

PATENT
Docket No. P1406

IN THE
UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: SERGEY LOPATIN

SERIAL NO.: 10/081,074

EXAMINER: UNASSIGNED

FILED: FEBRUARY 21, 2002

ART UNIT 2812

FOR: CHEMICAL SOLUTION FOR ELECTROPLATING A COPPER-
ZINC ALLOY THIN FILM

COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

Applicant hereby makes available the references listed on the enclosed form PTO-1449, Information Disclosure Statement by Applicant to assist the Patent and Trademark Office in its examination of this application.

The disclosure of the references does not constitute an admission that they are relevant or material to the claims or are "prior art" to the subject application. No representation is made that better references do not exist. Complete copies of the references are enclosed.

Respectfully submitted,

Victor Flores

Victor Flores

Reg. No. 29,638

VF/kr/sgs
June 14, 2002
LARIVIERE, GRUBMAN & PAYNE, LLP
PO Box 3140
Monterey, CA 93942
(831) 649-8800

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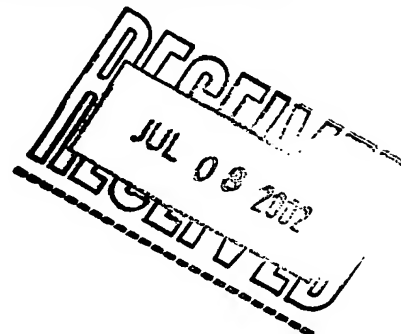
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TRANSMITTAL

Dear Sir:

In connection with the above referenced patent application, transmitted herewith are the following:

1. Information Disclosure Statement (1 page);
2. Information Disclosure Statement By Applicant Form PTO-1449 (1 page);
3. U.S. Patent No. 6,197,181 B1 (18 pages);
4. U.S. Patent No. 6,022,808 (6 pages);
5. Article "A Practical Guide to Semiconductor Processing" (3 pages);
6. Article "Electrochemical Codeposition and Electrical Characterization of a Copper-Zinc Alloy Metallization" (2 pages);
7. Article "Using Electrochemistry to Improve Copper Interconnect" (4 pages);
8. Article "ECD Seed Layer for Inlaid Copper Metallization" (2 pages); and

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9. Post card in acknowledgment of receipt of all transmitted materials.

Please date-stamp the enclosed postcard and return same to the undersigned in acknowledgment of receipt of all transmitted material.

Respectfully submitted,



Victor Flores
Reg. No. 29,638

VF/sgs
June 14, 2002
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Monterey, CA 93942
(831) 649-8800